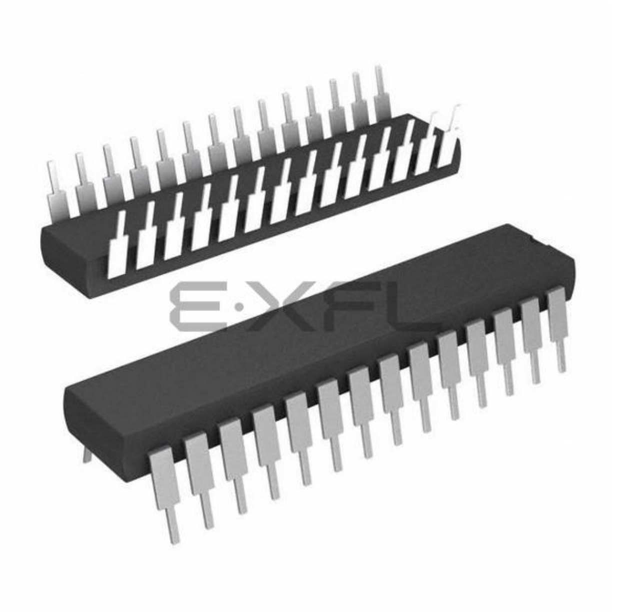
Microchip Technology - PIC16LC62A-04I/SP Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc62a-04i-sp

TABLE 4-5: SPECIAL FUNCTION REGISTERS FOR THE PIC16C65/65A/R65

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets(3)
Bank 0											
00h(1)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
01h	TMR0	Timer0 module’s register								xxxx xxxx	uuuu uuuu
02h(1)	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h(1)	STATUS	IRP(5)	RP1(5)	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	0001 1xxx	000q quuu
04h(1)	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
05h	PORTA	—	—	PORTA Data Latch when written: PORTA pins when read						--xx xxxx	--uu uuuu
06h	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
07h	PORTC	PORTC Data Latch when written: PORTC pins when read								xxxx xxxx	uuuu uuuu
08h	PORTD	PORTD Data Latch when written: PORTD pins when read								xxxx xxxx	uuuu uuuu
09h	PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -xxx	---- -uuu
0Ah(1,2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
0Bh(1)	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF	(6)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh	PIR2	—	—	—	—	—	—	—	CCP2IF	---- ---0	---- ---0
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
11h	TMR2	Timer2 module’s register								0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
15h	CCPR1L	Capture/Compare/PWM1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
19h	TXREG	USART Transmit Data Register								0000 0000	0000 0000
1Ah	RCREG	USART Receive Data Register								0000 0000	0000 0000
1Bh	CCPR2L	Capture/Compare/PWM2 (LSB)								xxxx xxxx	uuuu uuuu
1Ch	CCPR2H	Capture/Compare/PWM2 (MSB)								xxxx xxxx	uuuu uuuu
1Dh	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000
1Eh-1Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.
Shaded locations are unimplemented, read as ‘0’.

Note 1: These registers can be addressed from either bank.
2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)
3: Other (non power-up) resets include external reset through $\overline{\text{MCLR}}$ and the Watchdog Timer reset.
4: The $\overline{\text{BOR}}$ bit is reserved on the PIC16C65, always maintain this bit set.
5: The IRP and RP1 bits are reserved on the PIC16C65/65A/R65, always maintain these bits clear.
6: PIE1<6> and PIR1<6> are reserved on the PIC16C65/65A/R65, always maintain these bits clear.

4.2.2.6 PIE2 REGISTER

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

This register contains the CCP2 interrupt enable bit.

FIGURE 4-20: PIE2 REGISTER (ADDRESS 8Dh)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	CCP2IE
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7-1: **Unimplemented:** Read as '0'

bit 0: **CCP2IE**: CCP2 Interrupt Enable bit
1 = Enables the CCP2 interrupt
0 = Disables the CCP2 interrupt

4.2.2.8 PCON REGISTER

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The Power Control register (PCON) contains a flag bit to allow differentiation between a Power-on Reset to an external $\overline{\text{MCLR}}$ reset or WDT reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition.

Note: $\overline{\text{BOR}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOR}}$ is clear, indicating a brown-out has occurred. The $\overline{\text{BOR}}$ status bit is a “don't care” and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

FIGURE 4-22: PCON REGISTER FOR PIC16C62/64/65 (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q
—	—	—	—	—	—	$\overline{\text{POR}}$	—
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset
q = value depends on conditions

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{\text{POR}}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **Reserved**
This bit should be set upon a Power-on Reset by user software and maintained as set. Use of this bit as a general purpose read/write bit is not recommended, since this may affect upward compatibility with future products.

FIGURE 4-23: PCON REGISTER FOR PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67 (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q
—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOR}}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset
q = value depends on conditions

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{\text{POR}}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{\text{BOR}}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

NOTES:

5.2 PORTB and TRISB Register

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. Setting a bit in the TRISB register puts the corresponding output driver in a hi-impedance mode. Clearing a bit in the TRISB register puts the contents of the output latch on the selected pin(s).

EXAMPLE 5-2: INITIALIZING PORTB

```
BCF    STATUS, RP0  ;
CLRF   PORTB        ; Initialize PORTB by
                    ; clearing output
                    ; data latches
BSF    STATUS, RP0  ; Select Bank 1
MOVLW  0xCF         ; Value used to
                    ; initialize data
                    ; direction
MOVWF  TRISB        ; Set RB<3:0> as inputs
                    ; RB<5:4> as outputs
                    ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBPU}}$ (OPTION<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are also disabled on a Power-on Reset.

Four of PORTB's pins, RB7:RB4, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB port change interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.

b) Clear flag bit RBIF.

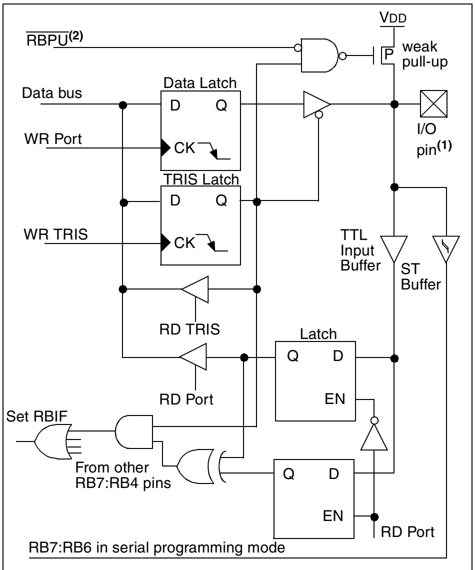
A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition, and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a keypad and make it possible for wake-up on key-depression. Refer to the Embedded Control Handbook, Application Note, *"Implementing Wake-up on Key Stroke" (AN552)*.

Note:	For PIC16C61/62/64/65, if a change on the I/O pin should occur when a read operation is being executed (start of the Q2 cycle), then interrupt flag bit RBIF may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 5-3: BLOCK DIAGRAM OF THE RB7:RB4 PINS FOR PIC16C61/62/64/65



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RPBU}}$ bit (OPTION<7>).

7.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control, i.e., it can be changed “on the fly” during program execution.

> **Note:** To avoid an unintended device RESET, the following instruction sequence (shown in Example 7-1) must be executed when changing the prescaler assignment from Timer0 to the WDT. This precaution must be followed even if the WDT is disabled.

EXAMPLE 7-1: CHANGING PRESCALER (TIMER0→WDT)

Lines 2 and 3 do NOT have to be included if the final desired prescale value is other than 1:1. If 1:1 is final desired value, then a temporary prescale value is set in lines 2 and 3 and the final prescale value will be set in lines 10 and 11.

```
1)  BSF    STATUS, RP0   ;Bank 1
2)  MOVLW  b'xx0x0xxx'   ;Select clock source and prescale value of
3)  MOVWF  OPTION_REG    ;other than 1:1
4)  BCF    STATUS, RP0   ;Bank 0
5)  CLRF   TMR0          ;Clear TMR0 and prescaler
6)  BSF    STATUS, RP1   ;Bank 1
7)  MOVLW  b'xxxx1xxx'   ;Select WDT, do not change prescale value
8)  MOVWF  OPTION_REG    ;
9)  CLRWDT               ;Clears WDT and prescaler
10) MOVLW  b'xxxx1xxx'   ;Select new prescale value and WDT
11) MOVWF  OPTION_REG    ;
12) BCF    STATUS, RP0   ;Bank 0
```

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 7-2.

EXAMPLE 7-2: CHANGING PRESCALER (WDT→TIMER0)

```
CLRWDT                ;Clear WDT and prescaler
BSF      STATUS, RP0 ;Bank 1
MOVLW    b'xxxx0xxx' ;Select TMR0, new prescale value and clock source
MOVWF    OPTION_REG  ;
BCF      STATUS, RP0 ;Bank 0
```

TABLE 7-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h, 101h	TMR0	Timer0 module’s register								`xxxx xxxx`	`uuuu uuuu`
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE(1)	T0IE	INTE	RBIE	T0IF	INTF	RBIF	`0000 000x`	`0000 000u`
81h, 181h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	`1111 1111`	`1111 1111`
85h	TRISA	—	—	PORTA Data Direction Register(1)						`--11 1111`	`--11 1111`

Legend: `x` = unknown, `u` = unchanged, `-` = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

Note 1: TRISA<5> and bit PEIE are not implemented on the PIC16C61, read as '0'.

11.2 SPI Mode for PIC16C62/62A/R62/63/R63/64/64A/R64/65/65A/R65

This section contains register definitions and operational characteristics of the SPI module for the PIC16C62, PIC16C62A, PIC16CR62, PIC16C63, PIC16CR63, PIC16C64, PIC16C64A, PIC16CR64, PIC16C65, PIC16C65A, PIC16CR65.

FIGURE 11-1: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS 94h)

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	$D/\overline{A}$	P	S	$R/\overline{W}$	UA	BF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n =Value at POR reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5: **$D/\overline{A}$**: Data/Address bit (I^{2}C mode only)
1 = Indicates that the last byte received or transmitted was data
0 = Indicates that the last byte received or transmitted was address

bit 4: **P**: Stop bit (I^{2}C mode only. This bit is cleared when the SSP module is disabled, SSPEN is cleared)
1 = Indicates that a stop bit has been detected last (this bit is '0' on RESET)
0 = Stop bit was not detected last

bit 3: **S**: Start bit (I^{2}C mode only. This bit is cleared when the SSP module is disabled, SSPEN is cleared)
1 = Indicates that a start bit has been detected last (this bit is '0' on RESET)
0 = Start bit was not detected last

bit 2: **$R/\overline{W}$**: Read/Write bit information (I^{2}C mode only)
This bit holds the R/W bit information following the last address match. This bit is valid from the address match to the next start bit, stop bit, or $\overline{ACK}$ bit.
1 = Read
0 = Write

bit 1: **UA**: Update Address (10-bit I^{2}C mode only)
1 = Indicates that the user needs to update the address in the SSPADD register
0 = Address does not need to be updated

bit 0: **BF**: Buffer Full Status bit

Receive (SPI and I^{2}C modes)
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

Transmit (I^{2}C mode only)
1 = Transmit in progress, SSPBUF is full
0 = Transmit complete, SSPBUF is empty

TABLE 12-3: BAUD RATES FOR SYNCHRONOUS MODE

BAUD RATE (K)	FOSC = 20 MHz			16 MHz			10 MHz			7.15909 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1.2	NA	-	-	NA	-	-	NA	-	-	NA	-	-
2.4	NA	-	-	NA	-	-	NA	-	-	NA	-	-
9.6	NA	-	-	NA	-	-	9.766	+1.73	255	9.622	+0.23	185
19.2	19.53	+1.73	255	19.23	+0.16	207	19.23	+0.16	129	19.24	+0.23	92
76.8	76.92	+0.16	64	76.92	+0.16	51	75.76	-1.36	32	77.82	+1.32	22
96	96.15	+0.16	51	95.24	-0.79	41	96.15	+0.16	25	94.20	-1.88	18
300	294.1	-1.96	16	307.69	+2.56	12	312.5	+4.17	7	298.3	-0.57	5
500	500	0	9	500	0	7	500	0	4	NA	-	-
HIGH	5000	-	0	4000	-	0	2500	-	0	1789.8	-	0
LOW	19.53	-	255	15.625	-	255	9.766	-	255	6.991	-	255

BAUD RATE (K)	FOSC = 5.0688 MHz			4 MHz			3.579545 MHz			1 MHz			32.768 kHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-	0.303	+1.14	26
1.2	NA	-	-	NA	-	-	NA	-	-	1.202	+0.16	207	1.170	-2.48	6
2.4	NA	-	-	NA	-	-	NA	-	-	2.404	+0.16	103	NA	-	-
9.6	9.6	0	131	9.615	+0.16	103	9.622	+0.23	92	9.615	+0.16	25	NA	-	-
19.2	19.2	0	65	19.231	+0.16	51	19.04	-0.83	46	19.24	+0.16	12	NA	-	-
76.8	79.2	+3.13	15	76.923	+0.16	12	74.57	-2.90	11	83.34	+8.51	2	NA	-	-
96	97.48	+1.54	12	1000	+4.17	9	99.43	+3.57	8	NA	-	-	NA	-	-
300	316.8	+5.60	3	NA	-	-	298.3	-0.57	2	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	1267	-	0	100	-	0	894.9	-	0	250	-	0	8.192	-	0
LOW	4.950	-	255	3.906	-	255	3.496	-	255	0.9766	-	255	0.032	-	255

TABLE 12-4: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

BAUD RATE (K)	FOSC = 20 MHz			16 MHz			10 MHz			7.15909 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1.2	1.221	+1.73	255	1.202	+0.16	207	1.202	+0.16	129	1.203	+0.23	92
2.4	2.404	+0.16	129	2.404	+0.16	103	2.404	+0.16	64	2.380	-0.83	46
9.6	9.469	-1.36	32	9.615	+0.16	25	9.766	+1.73	15	9.322	-2.90	11
19.2	19.53	+1.73	15	19.23	+0.16	12	19.53	+1.73	7	18.64	-2.90	5
76.8	78.13	+1.73	3	83.33	+8.51	2	78.13	+1.73	1	NA	-	-
96	104.2	+8.51	2	NA	-	-	NA	-	-	NA	-	-
300	312.5	+4.17	0	NA	-	-	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	312.5	-	0	250	-	0	156.3	-	0	111.9	-	0
LOW	1.221	-	255	0.977	-	255	0.6104	-	255	0.437	-	255

BAUD RATE (K)	FOSC = 5.0688 MHz			4 MHz			3.579545 MHz			1 MHz			32.768 kHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	0.31	+3.13	255	0.3005	-0.17	207	0.301	+0.23	185	0.300	+0.16	51	0.256	-14.67	1
1.2	1.2	0	65	1.202	+1.67	51	1.190	-0.83	46	1.202	+0.16	12	NA	-	-
2.4	2.4	0	32	2.404	+1.67	25	2.432	+1.32	22	2.232	-6.99	6	NA	-	-
9.6	9.9	+3.13	7	NA	-	-	9.322	-2.90	5	NA	-	-	NA	-	-
19.2	19.8	+3.13	3	NA	-	-	18.64	-2.90	2	NA	-	-	NA	-	-
76.8	79.2	+3.13	0	NA	-	-	NA	-	-	NA	-	-	NA	-	-
96	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
300	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	79.2	-	0	62.500	-	0	55.93	-	0	15.63	-	0	0.512	-	0
LOW	0.3094	-	255	3.906	-	255	0.2185	-	255	0.0610	-	255	0.0020	-	255

13.5 Interrupts

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The PIC16C6X family has up to 11 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or global enable bit, GIE.

Global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in the INTCON register. GIE is cleared on reset.

The "return from interrupt" instruction, `RETFIE`, exits the interrupt routine as well as sets the GIE bit, which re-enable interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flag bits are contained in the INTCON register.

The peripheral interrupt flag bits are contained in special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2 and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, bit GIE is cleared to disable any further interrupts, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the RB0/INT pin or RB port change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 13-19). The latency is the same for one or two cycle instructions. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid infinite interrupt requests. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

Note: For the PIC16C61/62/64/65, if an interrupt occurs while the Global Interrupt Enable bit, GIE is being cleared, bit GIE may unintentionally be re-enabled by the user's Interrupt Service Routine (the `RETFIE` instruction). The events that would cause this to occur are:

1. An instruction clears the GIE bit while an interrupt is acknowledged
2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
3. The Interrupt Service Routine completes with the execution of the `RETFIE` instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.
4. Perform the following to ensure that interrupts are globally disabled.

```
LOOP BCF INTCON,GIE    ;Disable Global
                       ;Interrupt bit
     BTFSC INTCON,GIE  ;Global Interrupt
                       ;Disabled?
     GOTO  LOOP        ;NO, try again
     :                 ;Yes, continue
                       ;with program flow
```

13.7 Watchdog Timer (WDT)

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The Watchdog Timer is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device has been stopped, for example, by execution of a `SLEEP` instruction. During normal operation, a WDT time-out generates a device reset. If the device is in SLEEP mode, a WDT time-out causes the device to wake-up and continue with normal operation (WDT Wake-up). The WDT can be permanently disabled by clearing configuration bit WDTE (Section 13.1).

13.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The `CLRWDT` and `SLEEP` instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device RESET condition.

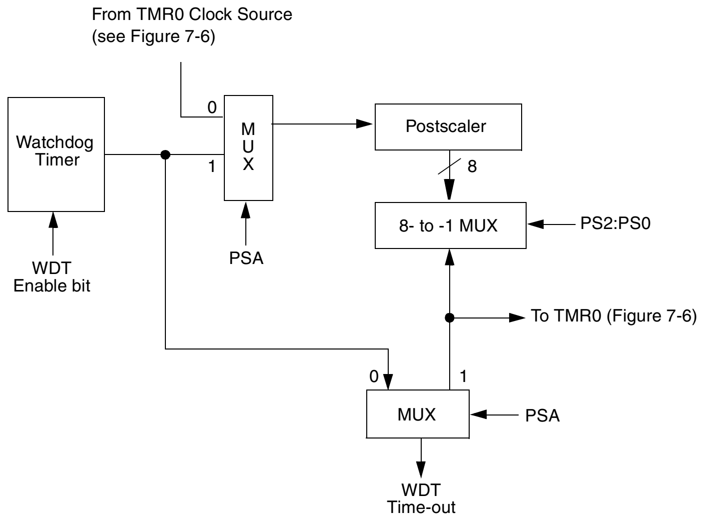
The $\overline{\text{TO}}$ bit in the STATUS register will be cleared upon a WDT time-out.

13.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken in account that under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler) it may take several seconds before a WDT time-out occurs.

Note: When a `CLRWDT` instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed.

FIGURE 13-20: WATCHDOG TIMER BLOCK DIAGRAM



Note: Bits T0CS, T0SE, PSA, PS2:PS0 are (OPTION<5:0>).

FIGURE 13-21: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	(1)	BODEN(1)	CP1	CP0	PWRTE(1)	WDTE	FOSC1	FOSC0
81h,181h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer.
Note 1: See Figure 13-1, Figure 13-2, and Figure 13-3 for details of these bits for the specific device.

13.8 Power-down Mode (SLEEP)

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

Power-down mode is entered by executing a `SLEEP` instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, status bit $\overline{\text{PD}}$ (STATUS<3>) is cleared, status bit $\overline{\text{TO}}$ (STATUS<4>) is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the `SLEEP` instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either VDD, or VSS, ensure no external circuitry is drawing current from the I/O pin, and disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{\text{MCLR}}$/VPP pin must be at a logic high level (VIHMC).

13.8.1 WAKE-UP FROM SLEEP

The device can wake from SLEEP through one of the following events:

1. External reset input on $\overline{\text{MCLR}}$/VPP pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from RB0/INT pin, RB port change, or some peripheral interrupts.

External $\overline{\text{MCLR}}$ Reset will cause a device reset. All other events are considered a continuation of program execution and cause a “wake-up”. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register can be used to determine the cause of device reset. The $\overline{\text{PD}}$ bit, which is set on power-up is cleared when `SLEEP` is invoked. The $\overline{\text{TO}}$ bit is cleared if WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from SLEEP:

1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
2. SSP (Start/Stop) bit detect interrupt.
3. SSP transmit or receive in slave mode (SPI/I^2C).
4. CCP capture mode interrupt.
5. Parallel Slave Port read or write.
6. USART TX or RX (synchronous slave mode).

Other peripherals can not generate interrupts since during SLEEP, no on-chip Q clocks are present.

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is set (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

13.8.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a `SLEEP` instruction, the `SLEEP` instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{\text{TO}}$ bit will not be set and $\overline{\text{PD}}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a `SLEEP` instruction, the device will immediately wake up from sleep. The `SLEEP` instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{\text{TO}}$ bit will be set and the $\overline{\text{PD}}$ bit will be cleared.

Even if the flag bits were checked before executing a `SLEEP` instruction, it may be possible for flag bits to become set before the `SLEEP` instruction completes. To determine whether a `SLEEP` instruction executed, test the $\overline{\text{PD}}$ bit. If the $\overline{\text{PD}}$ bit is set, the `SLEEP` instruction was executed as a NOP.

To ensure that the WDT is cleared, a `CLRWDT` instruction should be executed before a `SLEEP` instruction.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

DC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +125°C for extended, -40°C ≤ T_A ≤ +85°C for industrial and 0°C ≤ T_A ≤ +70°C for commercial Operating voltage V_{DD} range as described in DC spec Section 15.1 and Section 15.2.

Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
	Output High Voltage						
D090	I/O ports (Note 3)	V_{OH}	V_{DD}-0.7	-	-	V	I_{OH} = -3.0 mA, V_{DD} = 4.5V, -40°C to +85°C
D090A			V_{DD}-0.7	-	-	V	I_{OH} = -2.5 mA, V_{DD} = 4.5V, -40°C to +125°C
D092	OSC2/CLKOUT (RC osc config)		V_{DD}-0.7	-	-	V	I_{OH} = -1.3 mA, V_{DD} = 4.5V, -40°C to +85°C
D092A			V_{DD}-0.7	-	-	V	I_{OH} = -1.0 mA, V_{DD} = 4.5V, -40°C to +125°C
D150*	**Open-Drain High Voltage**	V_{OD}	-	-	14	V	RA4 pin
	Capacitive Loading Specs on Output Pins						
D100	OSC2 pin	C_{OSC2}			15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	C_{IO}			50	pF	

* The parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$/V_{PP} pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

18.1 DC Characteristics: PIC16C62A/R62/64A/R64-04 (Commercial, Industrial, Extended) PIC16C62A/R62/64A/R64-10 (Commercial, Industrial, Extended) PIC16C62A/R62/64A/R64-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)
Operating temperature -40°C ≤ TA ≤ +125°C for extended,
-40°C ≤ TA ≤ +85°C for industrial and
0°C ≤ TA ≤ +70°C for commercial

Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001	Supply Voltage	VDD	4.0	-	6.0	V	XT, RC and LP osc configuration
D001A			4.5	-	5.5	V	HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
			3.7	4.0	4.4	V	Extended Range Only
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5	mA	XT, RC, osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	mA	HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	µA	BOR enabled, VDD = 5.0V
D020	Power-down Current (Note 3, 5)	IPD	-	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	16	µA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	2.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	µA	BOR enabled, VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

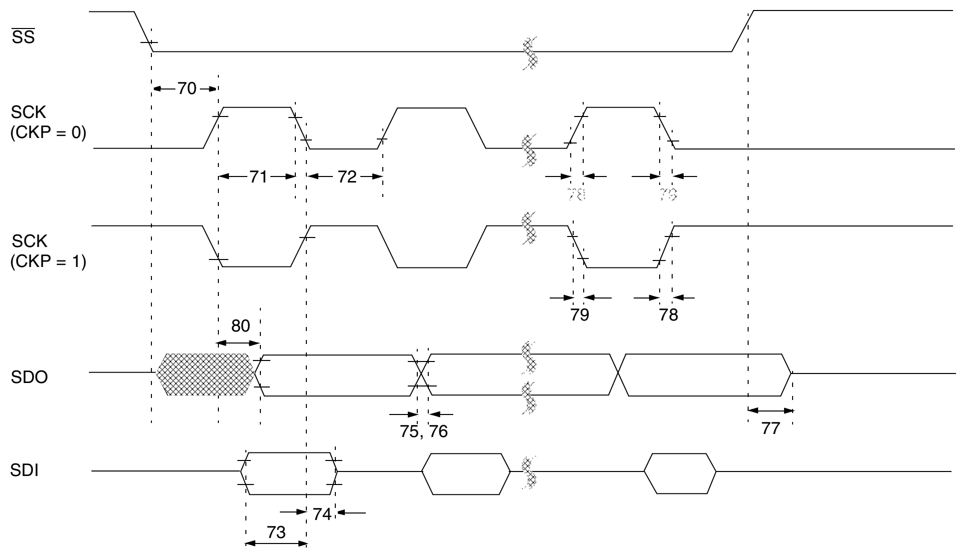
3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

FIGURE 18-9: SPI MODE TIMING



Note: Refer to Figure 18-1 for load conditions

TABLE 18-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{\text{SS}}$↓ to SCK↓ or SCK↑ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{\text{SS}}$↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

21.3 DC Characteristics: PIC16CR63/R65-04 (Commercial, Industrial)
PIC16CR63/R65-10 (Commercial, Industrial)
PIC16CR63/R65-20 (Commercial, Industrial)
PIC16LCR63/R65-04 (Commercial, Industrial)

DC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 21.1 and Section 21.2						
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15VDD	V	For entire VDD range
D030A			VSS	-	0.8V	V	4.5V ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		VSS	-	0.2VDD	V	
D032	$\overline{\text{MCLR}}$, OSC1 (in RC mode)		Vss	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	-	VDD	V	For entire VDD range
D042	$\overline{\text{MCLR}}$		0.8VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	400	µA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{\text{MCLR}}$, RA4/T0CKI		-	-	±5	µA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D150*	**Open-Drain High Voltage**	VOD	-	-	14	V	RA4 pin

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

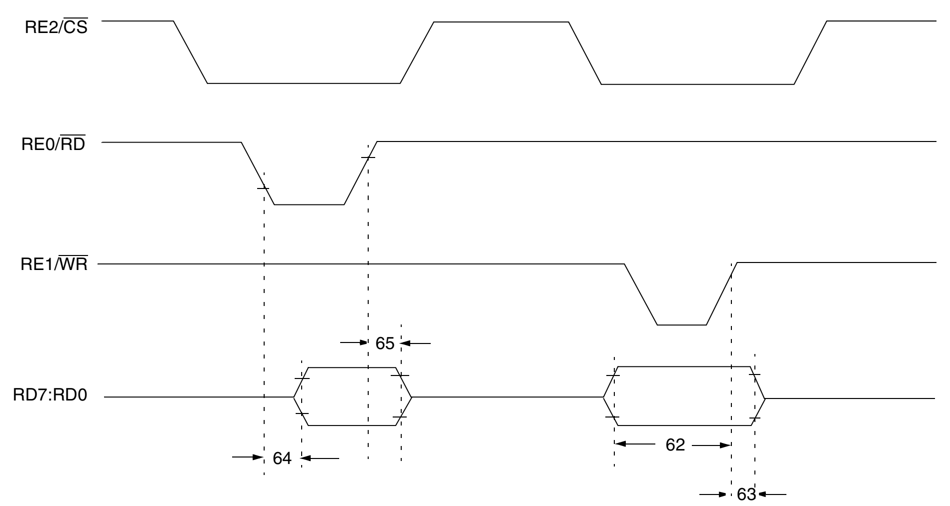
Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 21-8: PARALLEL SLAVE PORT TIMING (PIC16CR65)



Note: Refer to Figure 21-1 for load conditions

TABLE 21-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16CR65)

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
62*	TdtV2wrH	Data in valid before $\overline{\text{WR}}$↑ or $\overline{\text{CS}}$↑ (setup time)		20	—	—	ns	
63*	TwrH2dtI	$\overline{\text{WR}}$↑ or $\overline{\text{CS}}$↑ to data–in invalid (hold time)	PIC16**CR**65	20	—	—	ns	
			PIC16**LCR**65	35	—	—	ns	
64	TrdL2dtV	$\overline{\text{RD}}$↓ and $\overline{\text{CS}}$↓ to data–out valid		—	—	80	ns	
65*	TrdH2dtI	$\overline{\text{RD}}$↑ or $\overline{\text{CS}}$↑ to data–out invalid		10	—	30	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 21-12: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

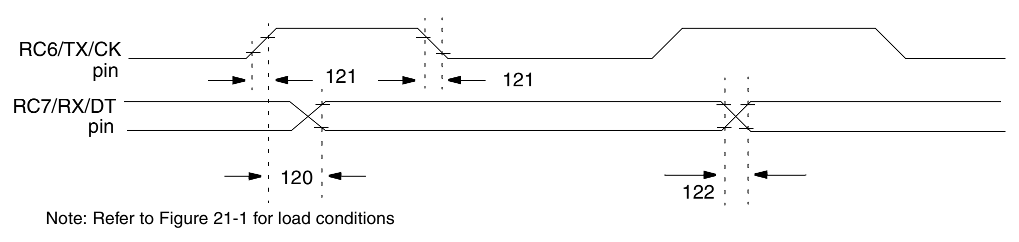


TABLE 21-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120*	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	PIC16**CR**63/R65	—	—	80	ns	
			PIC16**LCR**63/R65	—	—	100	ns	
121*	Tckrf	Clock out rise time and fall time (Master Mode)	PIC16**CR**63/R65	—	—	45	ns	
			PIC16**LCR**63/R65	—	—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16**CR**63/R65	—	—	45	ns	
			PIC16**LCR**63/R65	—	—	50	ns	

* These parameters are characterized but not tested.

†: Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 21-13: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

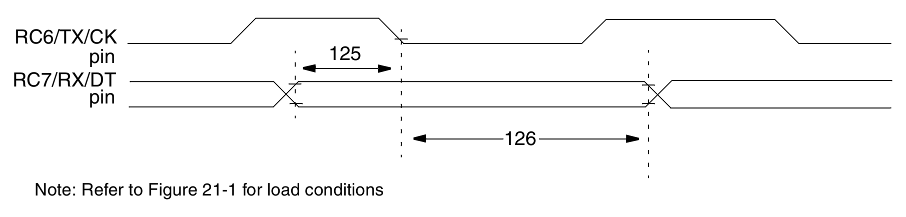


TABLE 21-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125*	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126*	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

* These parameters are characterized but not tested.

†: Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 23-25: TYPICAL IDD vs. FREQUENCY (LP MODE, 25°C)

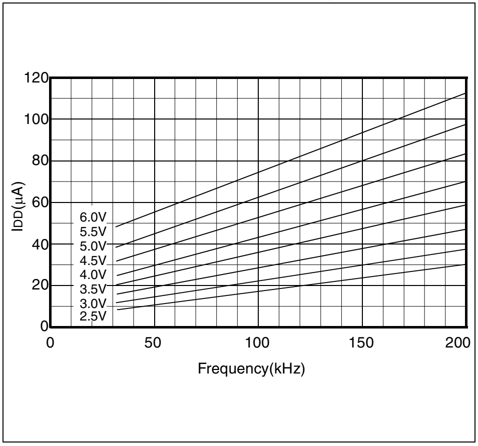


FIGURE 23-26: MAXIMUM IDD vs. FREQUENCY (LP MODE, 85°C TO -40°C)

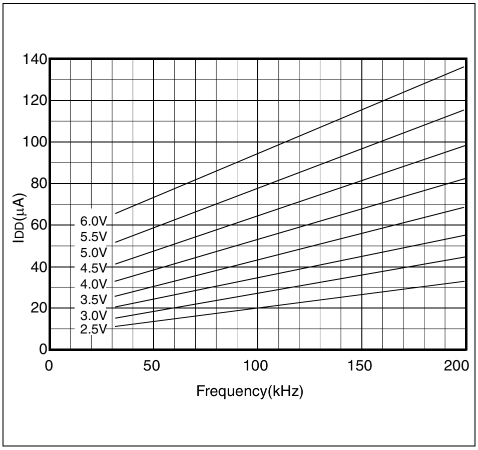


FIGURE 23-27: TYPICAL IDD vs. FREQUENCY (XT MODE, 25°C)

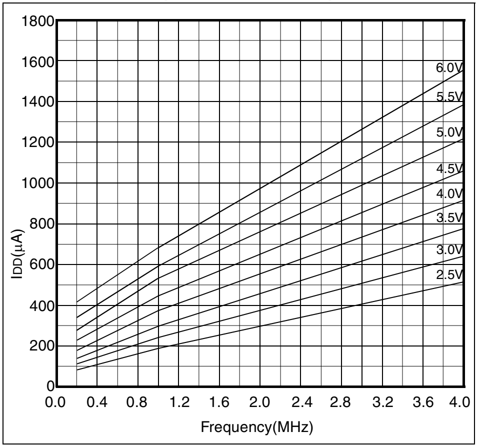
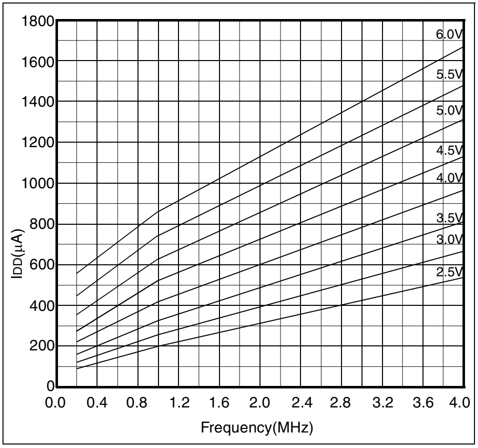


FIGURE 23-28: MAXIMUM IDD vs. FREQUENCY (XT MODE, -40°C TO 85°C)



Data based on matrix samples. See first page of this section for details.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 23-29: TYPICAL IDD vs. FREQUENCY (HS MODE, 25°C)

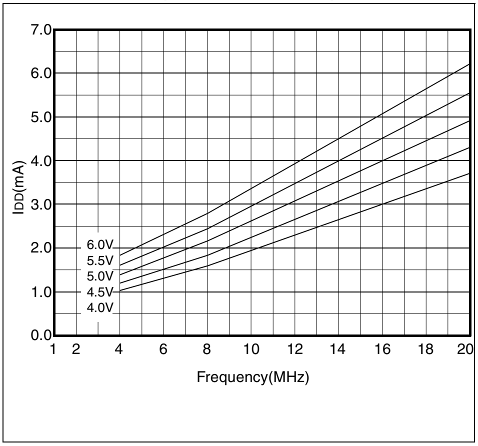
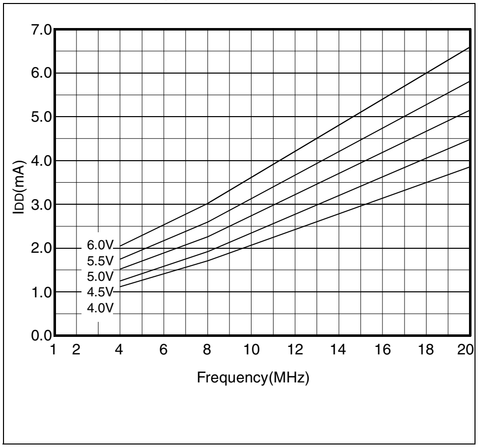


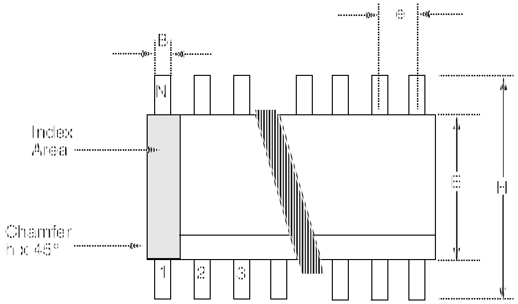
FIGURE 23-30: MAXIMUM IDD vs. FREQUENCY (HS MODE, -40°C TO 85°C)

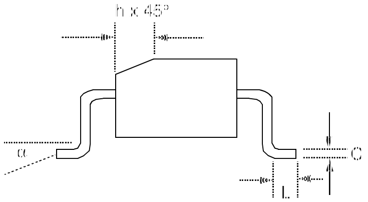


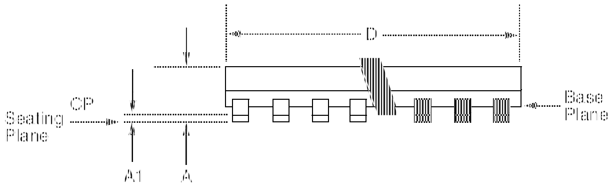
Data based on matrix samples. See first page of this section for details.

24.5 28-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging







Package Group: Plastic SOIC (SO)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	2.362	2.642		0.093	0.104	
A1	0.101	0.300		0.004	0.012	
B	0.355	0.483		0.014	0.019	
C	0.241	0.318		0.009	0.013	
D	17.703	18.085		0.697	0.712	
E	7.416	7.595		0.292	0.299	
e	1.270	1.270	**Typical**	0.050	0.050	**Typical**
H	10.007	10.643		0.394	0.419	
h	0.381	0.762		0.015	0.030	
L	0.406	1.143		0.016	0.045	
N	28	28		28	28	
CP	–	0.102		–	0.004	